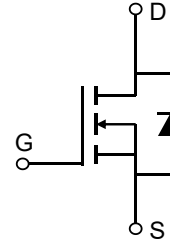


### Description

#### Features

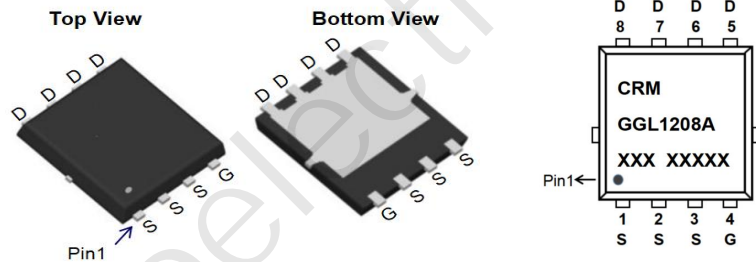
- 120V, 90A
- $R_{DS(ON)}$  Typ = 6.0mΩ @  $V_{GS} = 10V$
- $R_{DS(ON)}$  Typ = 7.3mΩ @  $V_{GS} = 4.5V$
- Advanced Split Gate Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- 100% UIS TESTED!
- 100%  $\Delta V_{ds}$  TESTED!



Schematic Diagram

#### Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

#### Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMGGL1208A	CRMGGL1208A	PDFN5x6-8L	TAPING	13"	5000	50000

#### Absolute Maximum Ratings (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units
$V_{DS}$	Drain-to-Source Voltage	120	V
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current	$T_C = 25^\circ\text{C}$	90
		$T_C = 100^\circ\text{C}$	54
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>	360	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>(2)</sup>	210	mJ
$P_D$	Power Dissipation	$T_C = 25^\circ\text{C}$	125
$R_{\theta JC}$	Thermal Resistance, Junction to Case	1	$^\circ\text{C/W}$
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55 to 150	$^\circ\text{C}$

### Electrical Characteristics ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
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#### Off Characteristics

$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}$ , $V_{GS} = 0\text{V}$	120	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 120\text{V}$ , $V_{GS} = 0\text{V}$	-	-	1.0	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{DS} = 0\text{V}$ , $V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA

#### On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 250\mu\text{A}$	1.4	2	2.6	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance <sup>(3)</sup>	$V_{GS} = 10\text{V}$ , $I_D = 30\text{A}$	-	6	7.8	mΩ
		$V_{GS} = 4.5\text{V}$ , $I_D = 20\text{A}$	-	7.3	9.5	mΩ

#### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{GS} = 0\text{V}$ , $V_{DS} = 60\text{V}$ , $f = 1\text{MHz}$	-	3494	-	pF
$C_{oss}$	Output Capacitance		-	1066	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	19	-	pF
$Q_g$	Total Gate Charge	$V_{GS} = 0$ to $10\text{V}$ $V_{DS} = 60\text{V}$ , $I_D = 20\text{A}$	-	40	-	nC
$Q_{gs}$	Gate Source Charge		-	9	-	nC
$Q_{gd}$	Gate Drain("Miller") Charge		-	10	-	nC

#### Switching Characteristics

$t_{d(on)}$	Turn-On DelayTime	$V_{GS} = 10\text{V}$ , $V_{DD} = 60\text{V}$ $I_D = 30\text{A}$ , $R_{GEN} = 6\Omega$	-	13	-	ns
$t_r$	Turn-On Rise Time		-	25	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	38	-	ns
$t_f$	Turn-Off Fall Time		-	34	-	ns

#### Drain-Source Diode Characteristics and Max Ratings

$I_S$	Maximum Continuous Drain to Source Diode Forward Current	$V_{GS} = 0\text{V}$ , $I_S = 30\text{A}$	-	-	90	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current		-	-	360	A
$V_{SD}$	Drain to Source Diode Forward Voltage		-	-	1.2	V
$t_{rr}$	Body Diode Reverse Recovery Time		-	65	-	ns
$Q_{rr}$	Body Diode Reverse Recovery Charge		-	70	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
  2.  $E_{AS}$  condition: Starting  $T_J = 25^\circ\text{C}$ ,  $V_{DD} = 60\text{V}$ ,  $V_G = 10\text{V}$ ,  $R_G = 25\text{ohm}$ ,  $L = 0.5\text{mH}$ ,  $I_{AS} = 29\text{A}$
  3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$ .

## Typical Performance Characteristics

Figure 1: Output Characteristics

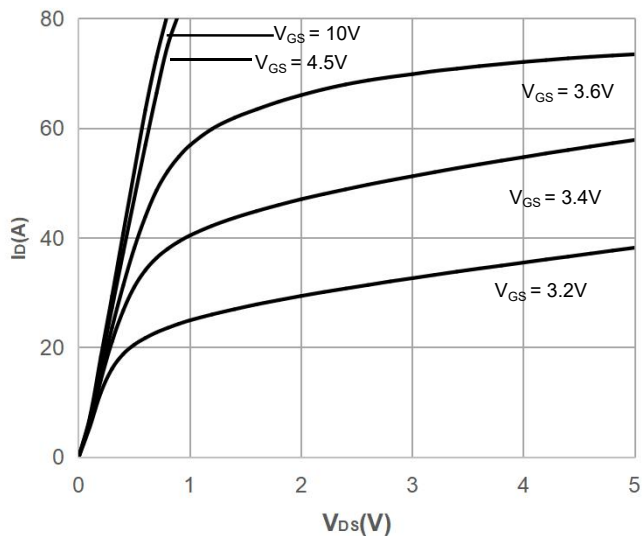


Figure 2: Typical Transfer Characteristics

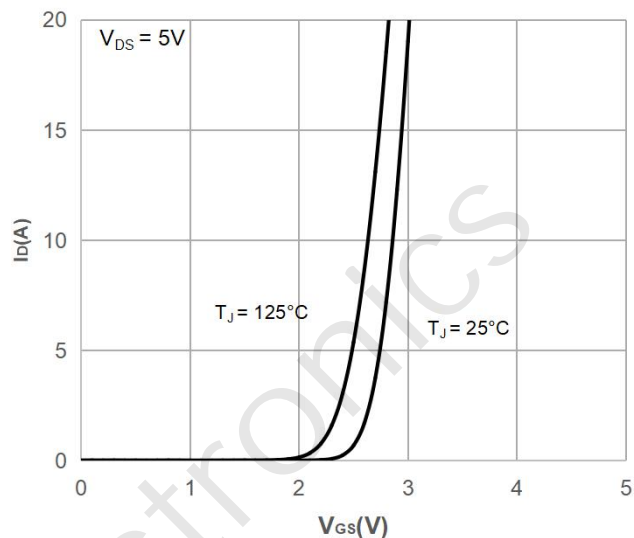


Figure 3: On-resistance vs. Drain Current

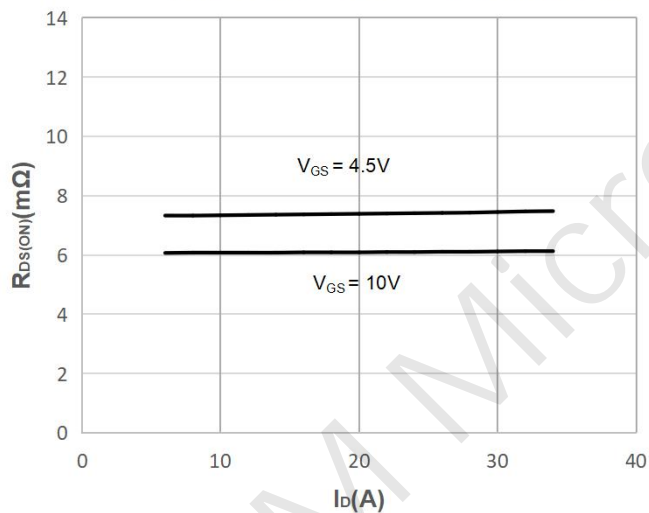


Figure 4: Body Diode Characteristics

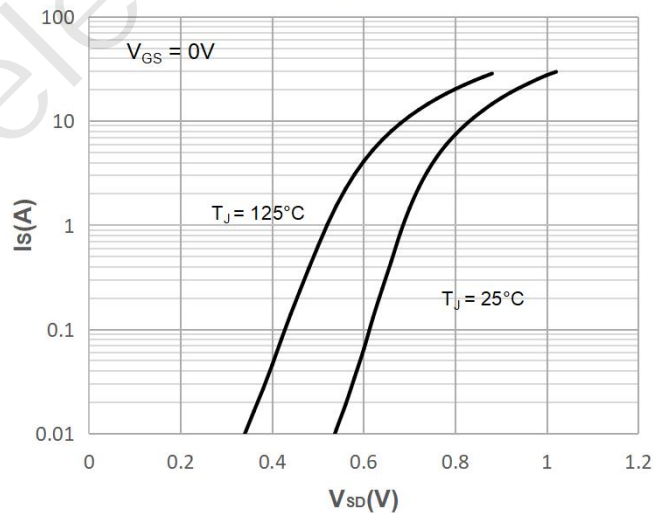


Figure 5: Gate Charge Characteristics

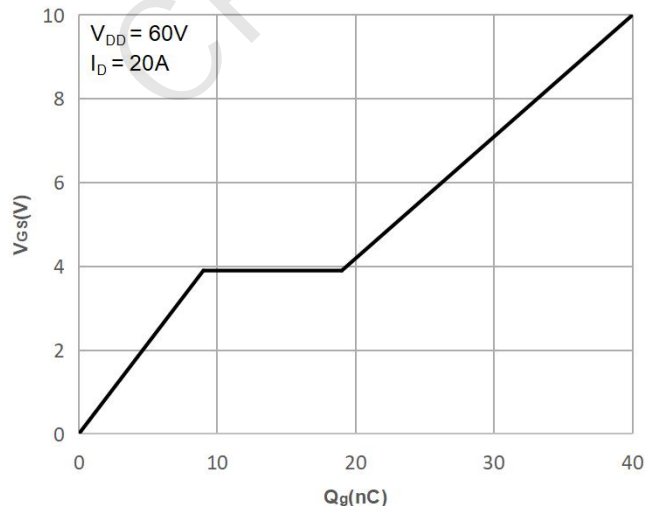
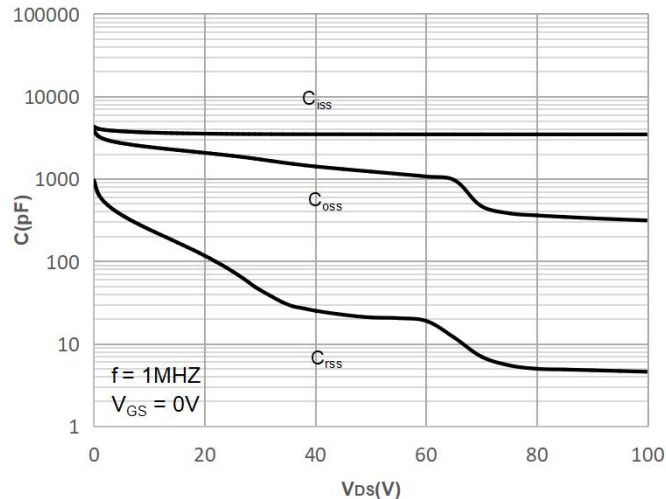


Figure 6: Capacitance Characteristics



## Typical Performance Characteristics

Figure 7: Normalized Breakdown voltage vs. Junction Temperature

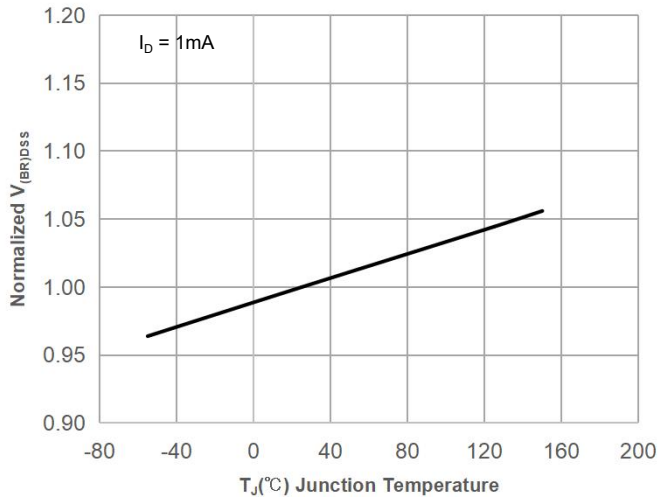


Figure 8: Normalized on Resistance vs. Junction Temperature

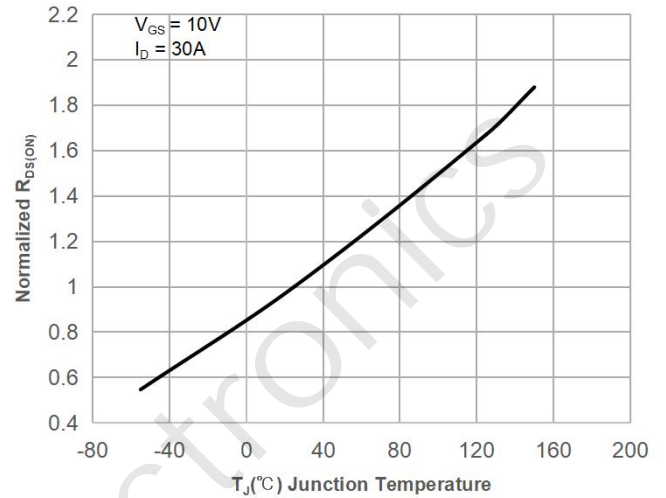


Figure 9: Maximum Safe Operating Area

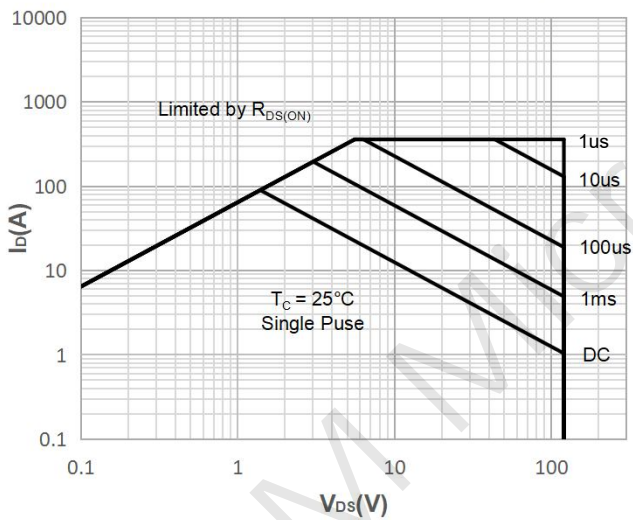


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

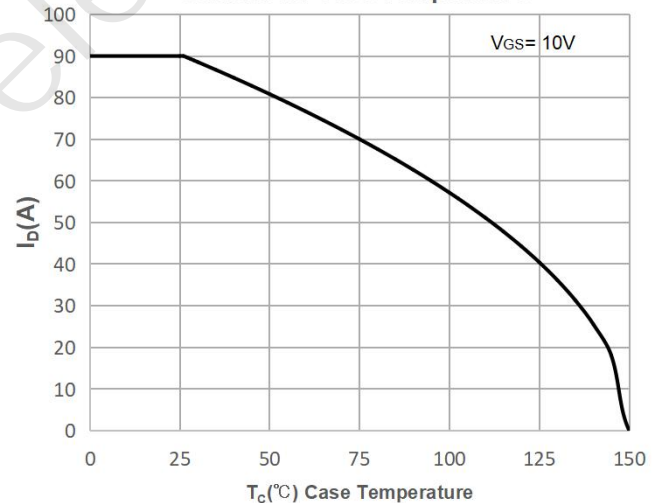


Figure 11: Normalized Maximum Transient Thermal Impedance

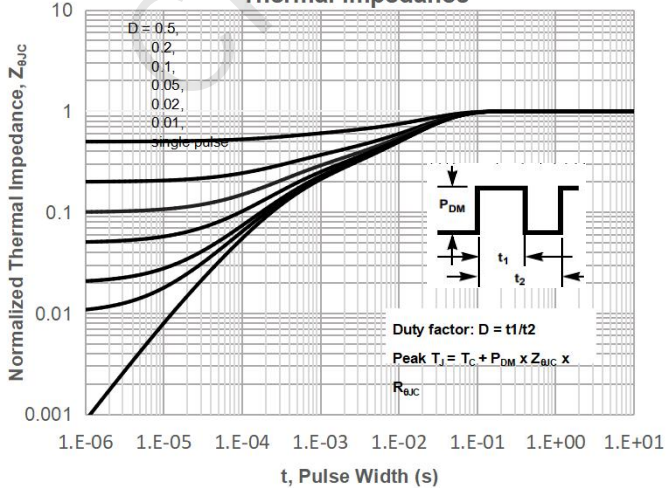
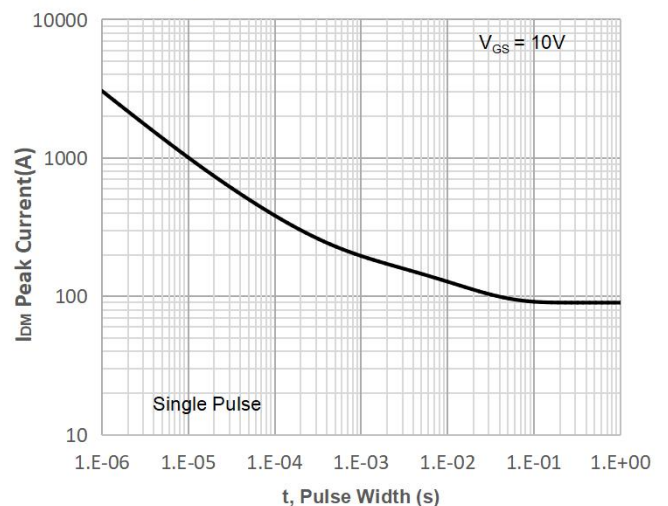


Figure 12: Peak Current Capacity



## Test Circuit

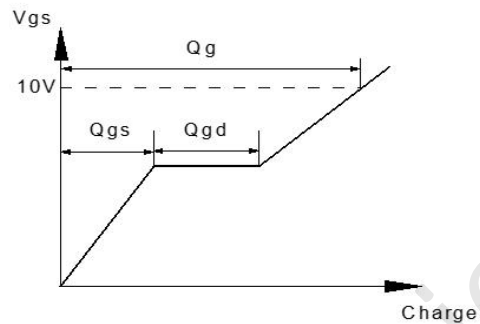
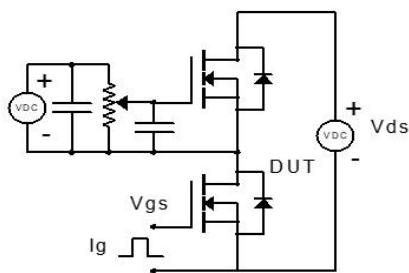


Figure 1: Gate Charge Test Circuit & Waveform

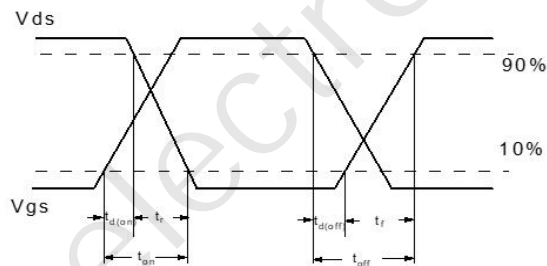
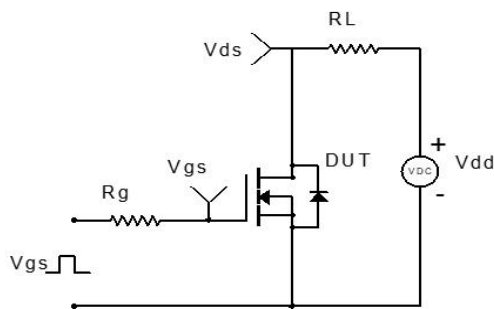


Figure 2: Resistive Switching Test Circuit & Waveform

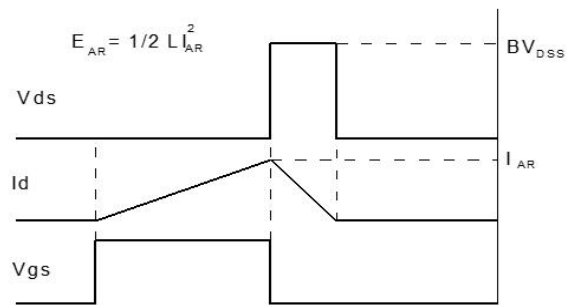
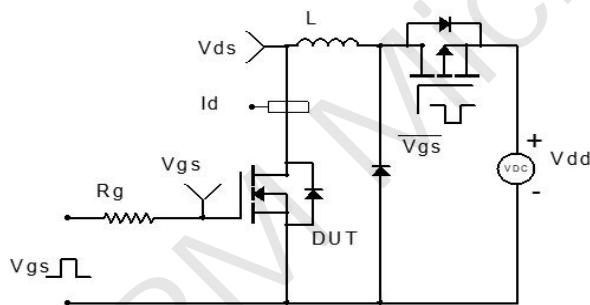


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

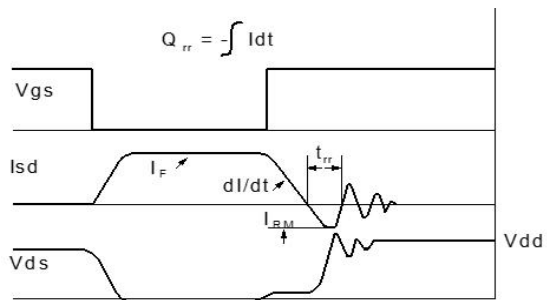
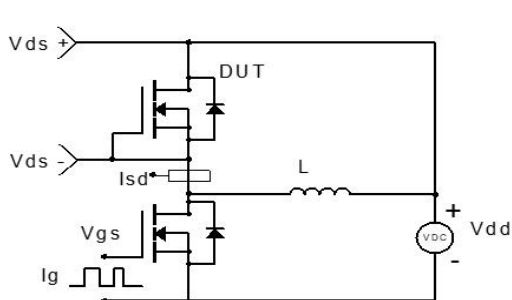
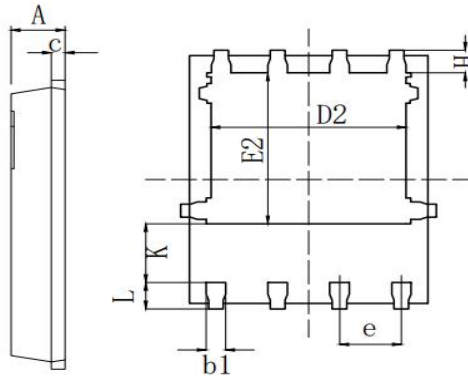
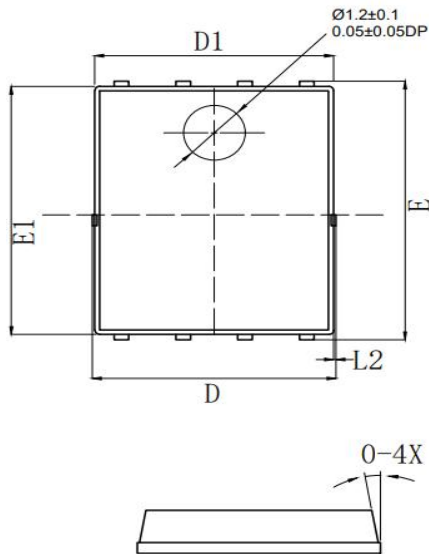


Figure 4: Diode Recovery Test Circuit & Waveform

### Package Mechanical Data(PDFN5x6-8L)




SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.90	1.00	1.10
b	0.25	0.30	0.35
b1	0.30	0.40	0.45
c	0.22	0.25	0.28
D	—	—	5.30
D1	4.90	5.05	5.20
D2	3.90REF		
E	6.00	6.15	6.30
E1	5.70	5.85	6.00
E2	3.50REF		
e	1.10	1.27	1.40
H	0.51	0.61	0.71
K	1.10	—	—
L	0.51	0.61	0.71
L2	—	—	0.10
Φ	8°	—	12°

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